

<u>mailto:processchange@centralsemi.com</u> <u>http://www.centralsemi.com/processchange</u>

PCN #255 Notification Date: July 23, 2024

Product / Process Change Notice

Devices affected:

All devices manufactured in the TO-72 case as well as the 2N5116.

Extent of change:

Replacement of aging nickel plating line with new nickel plating line for headers used in the assembly of the listed devices.

Reason for change:

As part of Central Semiconductor's supply chain risk mitigation initiative, in an effort to ensure an undisrupted supply of product, a change in the nickel plating line is being made for the referenced product family. Product specifications, quality and reliability are not impacted by this addition.

Effect of change:

This change does not affect the fit, form or function of devices.

Qualification data:

Test	Condition	Failure Rate
Visual Inspection	Accordance with Specification	0/125
Plating Thickness	2.0 ~ 5.0 μm	0/10
High Temperature	No blistering/peeling on plating surface at 20X Magnification	0/10
Plating Adhesion	No blistering/peeling on plating surface at 20X Magnification	0/10
Hermeticity	1X10⁻⁵atm • cc/sec Max.	0/10
Insulation Resistance	$6 \times 10^9 \Omega$ Min.	0/10
Bonding Strength	BPT : 4g Min. Not allowed Failure(X,∇)	0/10

Earliest effective date of change:

October 23, 2024

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Sample availability:

Please contact your salesperson or manufacturer's representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	

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